Intel - EP4CE115F29C8N Datasheet





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Details

Product Status	Active
Number of LABs/CLBs	7155
Number of Logic Elements/Cells	114480
Total RAM Bits	3981312
Number of I/O	528
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce115f29c8n

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Section I. Device Core

This section provides a complete overview of all features relating to the Cyclone[®] IV device family, which is the most architecturally advanced, high-performance, low-power FPGA in the marketplace. This section includes the following chapters:

- Chapter 1, Cyclone IV FPGA Device Family Overview
- Chapter 2, Logic Elements and Logic Array Blocks in Cyclone IV Devices
- Chapter 3, Memory Blocks in Cyclone IV Devices
- Chapter 4, Embedded Multipliers in Cyclone IV Devices
- Chapter 5, Clock Networks and PLLs in Cyclone IV Devices

Revision History

Refer to each chapter for its own specific revision history. For information about when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

2. Logic Elements and Logic Array Blocks in Cyclone IV Devices

CYIV-51002-1.0

This chapter contains feature definitions for logic elements (LEs) and logic array blocks (LABs). Details are provided on how LEs work, how LABs contain groups of LEs, and how LABs interface with the other blocks in Cyclone[®] IV devices.

Logic Elements

Logic elements (LEs) are the smallest units of logic in the Cyclone IV device architecture. LEs are compact and provide advanced features with efficient logic usage. Each LE has the following features:

- A four-input look-up table (LUT), which can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive the following interconnects:
 - Local
 - Row
 - Column
 - Register chain
 - Direct link
- Register packing support
- Register feedback support



In true dual-port mode, you can access any memory location at any time from either port A or port B. However, when accessing the same memory location from both ports, you must avoid possible write conflicts. When you attempt to write to the same address location from both ports at the same time, a write conflict happens. This results in unknown data being stored to that address location. There is no conflict resolution circuitry built into the Cyclone IV devices M9K memory blocks. You must handle address conflicts external to the RAM block.

Figure 3–11 shows true dual-port timing waveforms for the write operation at port A and read operation at port B. Registering the outputs of the RAM simply delays the q outputs by one clock cycle.



Figure 3–11. Cyclone IV Devices True Dual-Port Timing Waveform

Shift Register Mode

Cyclone IV devices M9K memory blocks can implement shift registers for digital signal processing (DSP) applications, such as finite impulse response (FIR) filters, pseudo-random number generators, multi-channel filtering, and auto-correlation and cross-correlation functions. These and other DSP applications require local data storage, traditionally implemented with standard flipflops that quickly exhaust many logic cells for large shift registers. A more efficient alternative is to use embedded memory as a shift register block, which saves logic cell and routing resources.

The size of a $(w \times m \times n)$ shift register is determined by the input data width (w), the length of the taps (m), and the number of taps (n), and must be less than or equal to the maximum number of memory bits, which is 9,216 bits. In addition, the size of $(w \times n)$ must be less than or equal to the maximum width of the block, which is 36 bits. If you need a larger shift register, you can cascade the M9K memory blocks.

9-Bit Multipliers

You can configure each embedded multiplier to support two 9×9 independent multipliers for input widths of up to 9 bits.

Figure 4–4 shows the embedded multiplier configured to support two 9-bit multipliers.





All 9-bit multiplier inputs and results are independently sent through registers. The multiplier inputs can accept signed integers, unsigned integers, or a combination of both. Two 9 × 9 multipliers in the same embedded multiplier block share the same signa and signb signal. Therefore, all the Data A inputs feeding the same embedded multiplier must have the same sign representation. Similarly, all the Data B inputs feeding the same embedded multiplier must have the same sign representation.

Clock Switchover

The clock switchover feature allows the PLL to switch between two reference input clocks. Use this feature for clock redundancy or for a dual-clock domain application, such as a system that turns on the redundant clock if the previous clock stops running. Your design can automatically perform clock switchover when the clock is no longer toggling, or based on the user control signal, clkswitch.

Automatic Clock Switchover

PLLs of Cyclone IV devices support a fully configurable clock switchover capability.

When the current reference clock is not present, the clock-sense block automatically switches to the backup clock for PLL reference. The clock switchover circuit also sends out three status signals—clkbad0, clkbad1, and activeclock—from the PLL to implement a custom switchover circuit. You can select a clock source at the backup clock by connecting it to the inclk1 port of the PLL in your design.

Figure 5–17 shows the block diagram of the switchover circuit built into the PLL.

Figure 5–17. Automatic Clock Switchover Circuit



There are two ways to use the clock switchover feature:

- Use the switchover circuitry for switching from inclk0 to inclk1 running at the same frequency. For example, in applications that require a redundant clock with the same frequency as the reference clock, the switchover state machine generates a signal that controls the multiplexer select input shown in Figure 5–17. In this case, inclk1 becomes the reference clock for the PLL. This automatic switchover can switch back and forth between the inclk0 and inclk1 clocks any number of times, when one of the two clocks fails and the other clock is available.
- Use the clkswitch input for user- or system-controlled switch conditions. This is possible for same-frequency switchover or to switch between inputs of different frequencies. For example, if inclk0 is 66 MHz and inclk1 is 200 MHz, you must control the switchover because the automatic clock-sense circuitry cannot monitor primary and secondary clock frequencies with a frequency difference of more than

Signal Name	Description	Source	Destination
scanclk	Free running clock from core used in combination with phasestep to enable or disable dynamic phase shifting. Shared with scanclk for dynamic reconfiguration.	GCLK or I/O pins	PLL reconfiguration circuit
phasedone	When asserted, it indicates to core logic that the phase adjustment is complete and PLL is ready to act on a possible second adjustment pulse. Asserts based on internal PLL timing. De-asserts on the rising edge of scanclk.	PLL reconfiguration circuit	Logic array or I/O pins

Table 5-12.	Dvnamic	Phase	Shiftina	Control	Signals	(Part 2 of 2	1
						1	

Table 5–13 lists the PLL counter selection based on the corresponding PHASECOUNTERSELECT setting.

Table 5–13. Phase Counter Select Mapping

	phasecounterselec	Salaata	
[2]	[1]	[0]	Selects
0	0	0	All Output Counters
0	0	1	M Counter
0	1	0	C0 Counter
0	1	1	C1 Counter
1	0	0	C2 Counter
1	0	1	C3 Counter
1	1	0	C4 Counter

To perform one dynamic phase-shift, follow these steps:

- 1. Set PHASEUPDOWN and PHASECOUNTERSELECT as required.
- 2. Assert PHASESTEP for at least two SCANCLK cycles. Each PHASESTEP pulse allows one phase shift.
- 3. Deassert PHASESTEP after PHASEDONE goes low.
- 4. Wait for PHASEDONE to go high.
- 5. Repeat steps 1 through 4 as many times as required to perform multiple phaseshifts.

<code>PHASEUPDOWN</code> and <code>PHASECOUNTERSELECT</code> signals are synchronous to <code>SCANCLK</code> and must meet the t_{su} and t_h requirements with respect to the <code>SCANCLK</code> edges.

You can repeat dynamic phase-shifting indefinitely. For example, in a design where the VCO frequency is set to 1,000 MHz and the output clock frequency is set to 100 MHz, performing 40 dynamic phase shifts (each one yields 125 ps phase shift) results in shifting the output clock by 180°, in other words, a phase shift of 5 ns.

Configuration Scheme

A configuration scheme with different configuration voltage standards is selected by driving the MSEL pins either high or low, as shown in Table 8–3, Table 8–4, and Table 8–5.

Hardwire the MSEL pins to V_{CCA} or GND without pull-up or pull-down resistors to avoid problems detecting an incorrect configuration scheme. Do not drive the MSEL pins with a microprocessor or another device.

Table 8-3.	Configuration Schemes for Cyclone IV GX Devices (EP4CGX15	EP4CGX22,	and EP4CGX30 [except for F484
Package])			

Configuration Scheme	MSEL2	MSEL1	MSELO	POR Delay	Configuration Voltage Standard (V) ⁽¹⁾
	1	0	1	Fast	3.3
٨٩	0	1	1	Fast	3.0, 2.5
AS	0	0	1	Standard	3.3
	0	1	0	Standard	3.0, 2.5
PS	1	0	0	Fast	3.3, 3.0, 2.5
	1	1	0	Fast	1.8, 1.5
	0	0	0	Standard	3.3, 3.0, 2.5
JTAG-based configuration ⁽²⁾	(3)	(3)	(3)	—	_

Notes to Table 8-3:

(1) Configuration voltage standard applied to the V_{CCIO} supply of the bank in which the configuration pins reside.

(2) JTAG-based configuration takes precedence over other configuration schemes, which means the MSEL pin settings are ignored.

(3) Do not leave the MSEL pins floating. Connect them to V_{CCA} or GND. These pins support the non-JTAG configuration scheme used in production. Altera recommends connecting the MSEL pins to GND if your device is only using JTAG configuration.

Table 8-4.	Configuration Schemes for Cyd	lone IV GX Devices (EP4CGX30 [only for F484 package], EP4CGX50,
EP4CGX75,	EP4CGX110, and EP4CGX150)	(Part 1 of 2)

Configuration Scheme	MSEL3	MSEL2	MSEL1	MSELO	POR Delay	Configuration Voltage Standard (V) ⁽¹⁾
	1	1	0	1	Fast	3.3
٨٩	1	0	1	1	Fast	3.0, 2.5
AS	1	0	0	1	Standard	3.3
	1	0	1	0	Standard	3.0, 2.5
	1	1	0	0	Fast	3.3, 3.0, 2.5
DC	1	1	1	0	Fast	1.8, 1.5
P3	1	0	0	0	Standard	3.3, 3.0, 2.5
	0	0	0	0	Standard	1.8, 1.5
FDD	0	0	1	1	Fast	3.3, 3.0, 2.5
	0	1	0	0	Fast	1.8, 1.5
	0	0	0	1	Standard	3.3, 3.0, 2.5
	0	0	1	0	Standard	1.8, 1.5

Table 8–4. Configuration Schemes for Cyclone IV GX Devices (EP4CGX30 [only for F484 package], EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150) (Part 2 of 2)

Configuration Scheme	MSEL3	MSEL2	MSEL1	MSELO	POR Delay	Configuration Voltage Standard (V) $^{(1)}$
JTAG-based configuration (2)	(3)	(3)	(3)	(3)	_	_

Notes to Table 8-4:

(1) Configuration voltage standard applied to the V_{CCIO} supply of the bank in which the configuration pins reside.

(2) JTAG-based configuration takes precedence over other configuration schemes, which means the MSEL pin settings are ignored.

(3) Do not leave the MSEL pins floating. Connect them to V_{CCA} or GND. These pins support the non-JTAG configuration scheme used in production. Altera recommends connecting the MSEL pins to GND if your device is only using JTAG configuration.

> Smaller Cyclone IV E devices or package options (E144 and F256 packages) do not have the MSEL[3] pin. The AS Fast POR configuration scheme at 3.0- or 2.5-V configuration voltage standard and the AP configuration scheme are not supported in Cyclone IV E devices without the MSEL[3] pin. To configure these devices with other supported configuration schemes, select MSEL[2..0] pins according to the MSEL settings in Table 8–5.

Configuration Scheme	MSEL3	MSEL2	MSEL1	MSELO	POR Delay	Configuration Voltage Standard (V) ⁽¹⁾
	1	1	0	1	Fast	3.3
۵۵	0	1	0	0	Fast	3.0, 2.5
AU	0	0	1	0	Standard	3.3
	0	0	1	1	Standard	3.0, 2.5
	0	1	0	1	Fast	3.3
AP	0	1	1	0	Fast	1.8
	0	1	1	1	Standard	3.3
	1	0	1	1	Standard	3.0, 2.5
	1	0	0	0	Standard	1.8
DC	1	1	0	0	Fast	3.3, 3.0, 2.5
10	0	0	0	0	Standard	3.3, 3.0, 2.5
EDD	1	1	1	0	Fast	3.3, 3.0, 2.5
	1	1	1	1	Fast	1.8, 1.5
JTAG-based configuration (2)	(3)	(3)	(3)	(3)	_	_

 Table 8–5.
 Configuration Schemes for Cyclone IV E Devices

Notes to Table 8-5:

(1) Configuration voltage standard applied to the V_{CCIO} supply of the bank in which the configuration pins reside.

(2) JTAG-based configuration takes precedence over other configuration schemes, which means the MSEL pin settings are ignored.

(3) Do not leave the MSEL pins floating. Connect them to V_{CCA} or GND. These pins support the non-JTAG configuration scheme used in production. Altera recommends connecting the MSEL pins to GND if your device is only using JTAG configuration. Figure 9–3 shows the error detection block diagram in FPGA devices and shows the interface that the WYSIWYG atom enables in your design.



Figure 9–3. Error Detection Block Diagram

The user logic is affected by the soft error failure, so reading out the 32-bit CRC signature through the regout should not be relied upon to detect a soft error. You should rely on the CRC_ERROR output signal itself, because this CRC_ERROR output signal cannot be affected by a soft error.

To enable the cycloneiv_crcblock WYSIWYG atom, you must name the atom for each Cyclone IV device accordingly.

Example 9–1 shows an example of how to define the input and output ports of a WYSIWYG atom in a Cyclone IV device.

Example 9–1. Error Detection Block Diagram

```
cycloneiv_crcblock<crcblock_name>
(
.clk(<clock source>),
.shiftnld(<shiftnld source>),
.ldsrc(<ldsrc source>),
.crcerror(<crcerror out destination>),
.regout(<output destination>),
);
```

10. JTAG Boundary-Scan Testing for Cyclone IV Devices

This chapter describes the boundary-scan test (BST) features that are supported in Cyclone[®] IV devices. The features are similar to Cyclone III devices, unless stated in this chapter.

Cyclone IV devices (Cyclone IV E devices and Cyclone IV GX devices) support IEEE Std. 1149.1. Cyclone IV GX devices also support IEEE Std. 1149.6. The IEEE Std. 1149.6 (AC JTAG) is only supported on the high-speed serial interface (HSSI) transceivers in Cyclone IV GX devices. The purpose of IEEE Std. 1149.6 is to enable board-level connectivity checking between transmitters and receivers that are AC coupled.

This chapter includes the following sections:

- "IEEE Std. 1149.6 Boundary-Scan Register" on page 10–2
- "BST Operation Control" on page 10–3
- "I/O Voltage Support in a JTAG Chain" on page 10–5
- "Boundary-Scan Description Language Support" on page 10–6
- **For more information about the JTAG instructions code with descriptions and IEEE** Std.1149.1 BST guidelines, refer to the *IEEE 1149.1 (JTAG) Boundary-Scan Testing for Cyclone III Devices* chapter.
- **To** For more information about the following topics, refer to *AN* 39: *IEEE* 1149.1 (*JTAG*) *Boundary-Scan Testing in Altera Devices*:
 - IEEE Std. 1149.1 BST architecture and circuitry
 - TAP controller state-machine
 - Instruction mode

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Visual Cue	Meaning
	Indicates signal, port, register, bit, block, and primitive names. For example, data1, tdi, and input. The suffix n denotes an active-low signal. For example, resetn.
Courier type	Indicates command line commands and anything that must be typed exactly as it appears. For example, c:\qdesigns\tutorial\chiptrip.gdf.
	Also indicates sections of an actual file, such as a Report File, references to parts of files (for example, the AHDL keyword SUBDESIGN), and logic function names (for example, TRI).
4	An angled arrow instructs you to press the Enter key.
1., 2., 3., and a., b., c., and so on	Numbered steps indicate a list of items when the sequence of the items is important, such as the steps listed in a procedure.
	Bullets indicate a list of items when the sequence of the items is not important.
LP	The hand points to information that requires special attention.
0	The question mark directs you to a software help system with related information.
	The feet direct you to another document or website with related information.
▋┯∎	The multimedia icon directs you to a related multimedia presentation.
CAUTION	A caution calls attention to a condition or possible situation that can damage or destroy the product or your work.
VIARNING	A warning calls attention to a condition or possible situation that can cause you injury.
	The envelope links to the Email Subscription Management Center page of the Altera website, where you can sign up to receive update notifications for Altera documents.

at time n + 2 is encoded as a positive disparity code group. In the same example, the current running disparity at time n + 5 indicates that the K28.5 in time n + 6 should be encoded with a positive disparity. Because tx_forcedisp is high at time n + 6, and tx_dispval is high, the K28.5 at time n + 6 is encoded as a negative disparity code group.

Miscellaneous Transmitter PCS Features

The transmitter PCS supports the following additional features:

Polarity inversion—corrects accidentally swapped positive and negative signals from the serial differential link during board layout by inverting the polarity of each bit. An optional tx_invpolarity port is available to dynamically invert the polarity of every bit of the 8-bit or 10-bit input data to the serializer in the transmitter datapath. Figure 1–9 shows the transmitter polarity inversion feature.

Figure 1–9. Transmitter Polarity Inversion



tx_invpolarity is a dynamic signal and might cause initial disparity errors at the receiver of an 8B/10B encoded link. The downstream system must be able to tolerate these disparity errors. The calibration block internally generates a constant internal reference voltage, independent of PVT variations and uses this voltage and the external reference resistor on the RREF pin to generate constant reference currents. The OCT calibration circuit calibrates the OCT resistors present in the transceiver channels. Figure 1–41 shows the calibration block diagram.





Notes to Figure 1-41:

- (1) All transceiver channels use the same calibration block clock and power down signals.
- (2) Connect a 2 k Ω (tolerance max ± 1%) external resistor to the RREF pin to ground. The RREF resistor connection in the board must be free from any external noise.
- (3) Supports up to 125 MHz clock frequency. Use either dedicated global clock or divide-down logic from the FPGA fabric to generate a slow clock on the local clock routing.
- (4) The calibration block restarts the calibration process following deassertion of the cal_blk_powerdown signal.

PCI-Express Hard IP Block

Figure 1–42 shows the block diagram of the PCIe hard IP block implementing the PHY MAC, Data Link Layer, and Transaction Layer for PCIe interfaces. The PIPE interface is used as the interface between the transceiver and the hard IP block.

Figure 1–42. PCI Express Hard IP High-Level Block Diagram



In Serial RapidIO mode, the rate match FIFO compensates up to ± 100 ppm (200 ppm total) difference between the upstream transmitter and the local receiver reference clock.

Rate matcher is an optional block available for selection in Serial RapidIO mode. However, this block is not fully compliant to the SRIO specification. When enabled in the ALTGX MegaWizard Plug-In Manager, the default settings are:

- control pattern 1 = K28.5 with positive disparity
- skip pattern 1 = K29.7 with positive disparity
- control pattern 2 = K28.5 with negative disparity
- skip pattern 2 = K29.7 with negative disparity

When enabled, the rate match FIFO operation begins after the link is synchronized (indicated by assertion of rx_syncstatus from the word aligner). When the rate matcher receives either of the two 10-bit control patterns followed by the respective 10-bit skip pattern, it inserts or deletes the 10-bit skip pattern as necessary to avoid the rate match FIFO from overflowing or under-running. The rate match FIFO can delete/insert a maximum of one skip pattern from a cluster.

The rate match FIFO may perform multiple insertion or deletion if the ppm difference is more than the allowable 200 ppm range. Ensure that the ppm difference in your system is less than 200 ppm.

XAUI Mode

XAUI mode provides the bonded (×4) transceiver channel datapath configuration for XAUI protocol implementation. The Cyclone IV GX transceivers configured in XAUI mode provides the following functions:

- XGMII-to-PCS code conversion at transmitter datapath
- PCS-to-XGMII code conversion at receiver datapath
- channel deskewing of four lanes
- 8B/10B encoding and decoding
- IEEE P802.3ae-compliant synchronization state machine
- clock rate compensation

The XAUI is a self-managed interface to transparently extend the physical reach of the XGMII between the reconciliation sublayer and the PHY layer in the 10 Gbps LAN as shown in Figure 1–62. The XAUI interface consists of four lanes, each running at 3.125 Gbps with 8B/10B encoded data for a total of actual 10 Gbps data throughput. At the transmit side of the XAUI interface, the data and control characters are

Figure 1–69 shows the transceiver configuration in SDI mode.



Figure 1–69. Transceiver Configuration in SDI Mode

Altera recommends driving rx_bitslip port low in configuration where low-latency PCS is not enabled. In SDI systems, the word alignment and framing occurs after descrambling, which is implemented in the user logic. The word alignment therefore is not useful, and keeping rx_bitslip port low avoids the word aligner from inserting bits in the received data stream.

Loopback

Cyclone IV GX devices provide three loopback options that allow you to verify the operation of different functional blocks in the transceiver channel. The following loopback modes are available:

- reverse parallel loopback (available only for PIPE mode)
- serial loopback (available for all modes except PIPE mode)
- reverse serial loopback (available for all modes except XAUI mode)

In each loopback mode, all transmitter buffer and receiver buffer settings are available if the buffers are active, unless stated otherwise.

Port Name	Input/ Output	Description				
		This is an optional equalizer DC gain write control.				
		The width of this signal is fixed to 2 bits if you enable either the Use 'logical_channel_address' port for Analog controls reconfiguration option or the Use same control signal for all the channels option in the Analog controls screen. Otherwise, the width of this signal is 2 bits per channel.				
		The following values are the legal settings allowed for this signal:				
		rx_eqdcgain[10] Corresponding ALTGX Corresponding				
rx_eqdcgain [10] ⁽¹⁾	Input	(dB) DC Gain value				
		2′b00 0 0				
		2'b01 1 3 ⁽²⁾				
		2'b10 2 6				
		All other values => N/A				
		For more information, refer to the "Programmable Equalization and DC Gain" section of the <i>Cyclone IV GX Device Datasheet</i> chapter.				
<pre>tx_vodctrl_out [20]</pre>	Output	This is an optional transmit V_{OD} read control signal. This signal reads out the value written into the V_{OD} control register. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the Use 'logical_channel_address' port for Analog controls reconfiguration option and the Use same control signal for all the channels option.				
tx_preemp_out [40]	Output	This is an optional pre-emphasis read control signal. This signal reads out the value writter by its input control signal. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the Use 'logical_channel_address' port for Analog controls reconfiguration option and the Use same control signal for all the channels option.				
rx_eqctrl_out [30]	Output	This is an optional read control signal to read the setting of equalization setting of the ALTGX instance. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the Use 'logical_channel_address' port for Analog controls reconfiguration option and the Use same control signal for all the channels option.				
rx_eqdcgain_out [10]	Output	This is an optional equalizer DC gain read control signal. This signal reads out the settings of the ALTGX instance DC gain. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the Use 'logical_channel_address' port for Analog controls reconfiguration option and the Use same control signal for all the channels option.				
Transceiver Channel Re	configura	tion Control/Status Signals				
		Set the following values at this signal to activate the appropriate dynamic reconfiguration mode:				
rogonfig mode		3'b000 = PMA controls reconfiguration mode. This is the default value.				
sel[20] ⁽³⁾	Input	3'b001 = Channel reconfiguration mode				
		All other values => N/A				
		reconfig_mode_sel[] is available as an input only when you enable more than one dynamic reconfiguration mode.				

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 6 of 7)

Clocking/Interface Options

The following describes the **Clocking/Interface** options available in Cyclone IV GX devices. The core clocking setup describes the transceiver core clocks that are the write and read clocks of the Transmit Phase Compensation FIFO and the Receive Phase Compensation FIFO, respectively. Core clocking is classified as transmitter core clocking and receiver core clocking.

Table 3–6 lists the supported clocking interface settings for channel reconfiguration mode in Cyclone IV GX devices.

ALTGX Setting	Description						
Dynamic Reconfiguration Channel Internal and Interface Settings							
	Select one of the available options:						
How should the receivers be	Share a single transmitter core clock between receivers						
clocked?	 Use the respective channel transmitter core clocks 						
	 Use the respective channel receiver core clocks 						
	Select one of the available options:						
How should the transmitters be	Share a single transmitter core clock between transmitters						
	 Use the respective channel transmitter core clocks 						

 Table 3–6. Dynamic Reconfiguration Clocking Interface Settings in Channel Reconfiguration

 Mode

Transmitter core clocking refers to the clock that is used to write the parallel data from the FPGA fabric into the Transmit Phase Compensation FIFO. You can use one of the following clocks to write into the Transmit Phase Compensation FIFO:

- tx_coreclk—you can use a clock of the same frequency as tx_clkout from the FPGA fabric to provide the write clock to the Transmit Phase Compensation FIFO. If you use tx_coreclk, it overrides the tx_clkout options in the ALTGX MegaWizard Plug-In Manager.
- tx_clkout—the Quartus II software automatically routes tx_clkout to the FPGA fabric and back into the Transmit Phase Compensation FIFO.

Functional Simulation of the Dynamic Reconfiguration Process

This section describes the points to be considered during functional simulation of the dynamic reconfiguration process.

- You must connect the ALTGX_RECONFIG instance to the ALTGX_instance/ALTGX instances in your design for functional simulation.
- The functional simulation uses a reduced timing model of the dynamic reconfiguration controller. The duration of the offset cancellation process is 16 reconfig_clk clock cycles for functional simulation only.
- The gxb_powerdown signal must not be asserted during the offset cancellation sequence (for functional simulation and silicon).

Document Revision History

Table 3–8 lists the revision history for this chapter.

 Table 3–8.
 Document Revision History

Date	Version	Changes
November 2011	2.1	 Updated "Dynamic Reconfiguration Controller Architecture", "PMA Controls Reconfiguration Mode", "PLL Reconfiguration Mode", and "Error Indication During Dynamic Reconfiguration" sections.
		■ Updated Table 3–2 and Table 3–4.
		 Updated for the Quartus II software version 10.1 release.
	2.0	■ Updated Table 3–1, Table 3–2, Table 3–3, Table 3–4, Table 3–5, and Table 3–6.
		■ Added Table 3–7.
December 2010		■ Updated Figure 3–1, Figure 3–11, Figure 3–13, and Figure 3–14.
		 Updated "Offset Cancellation Feature", "Error Indication During Dynamic Reconfiguration", "Data Rate Reconfiguration Mode Using RX Local Divider", "PMA Controls Reconfiguration Mode", and "Control and Status Signals for Channel Reconfiguration" sections.
July 2010	1.0	Initial release.

I/O Standard	V _{CCIO} (V)				V _{REF} (V)	V _{TT} (V) ⁽²⁾				
	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
SSTL-2 Class I, II	2.375	2.5	2.625	1.19	1.25	1.31	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04	
SSTL-18 Class I, II	1.7	1.8	1.9	0.833	0.9	0.969	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04	
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95	
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79	
HSTL-12	1 14	12	1 26	0.48 x V _{CCI0} <i>(3)</i>	0.5 x V _{CCIO} <i>(3)</i>	0.52 x V _{CCIO} <i>(3)</i>	_	0.5 x		
Class I, II	1.14	1.2	1.20	0.47 x V _{CCI0} (4)	0.5 x V _{CCIO} (4)	0.53 x V _{CCI0} (4)		V _{CCIO}		

Table 1–16.	Single-Ended SSTL and HSTL I/O Reference	Voltage Sr	pecifications for C	vclone IV Devices ⁽¹⁾
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Notes to Table 1–16:

(1) For an explanation of terms used in Table 1–16, refer to "Glossary" on page 1–37.

(2) $\,\,V_{TT}$ of the transmitting device must track V_{REF} of the receiving device.

(3) Value shown refers to DC input reference voltage, $V_{\text{REF(DC)}}.$

(4) Value shown refers to AC input reference voltage, $V_{\text{REF(AC)}}$.

Table 1–17.	Single-Ended SSTL	and HSTL I/O Standards Si	gnal Specifications for C	yclone IV Devices
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I/O	VIL	_{DC)} (V)	V _{IH(DC)} (V)		VIL	V _{IL(AC)} (V)		V _{IH(AC)} (V)		V _{oh} (V)	IOL	I _{OH}
Standard	Min	Max	Min	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mÄ)
SSTL-2 Class I	_	V _{REF} – 0.18	V _{REF} + 0.18	_	_	V _{REF} – 0.35	V _{REF} + 0.35	—	V _{TT} – 0.57	V _{TT} + 0.57	8.1	-8.1
SSTL-2 Class II	_	V _{REF} – 0.18	V _{REF} + 0.18	_	_	V _{REF} – 0.35	V _{REF} + 0.35	_	V _Π – 0.76	V _{TT} + 0.76	16.4	-16.4
SSTL-18 Class I	_	V _{REF} – 0.125	V _{REF} + 0.125	_	_	V _{REF} – 0.25	V _{REF} + 0.25	—	V _{TT} – 0.475	V _{TT} + 0.475	6.7	-6.7
SSTL-18 Class II	_	V _{REF} – 0.125	V _{REF} + 0.125	_	_	V _{REF} – 0.25	V _{REF} + 0.25	—	0.28	V _{CCI0} – 0.28	13.4	-13.4
HSTL-18 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	_	V _{REF} – 0.2	V _{REF} + 0.2	—	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	_	V _{REF} – 0.2	V _{REF} + 0.2	_	0.4	V _{CCI0} – 0.4	16	-16
HSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	_	V _{REF} – 0.2	V _{REF} + 0.2	_	0.4	V _{CCI0} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	_	V _{REF} – 0.2	V _{REF} + 0.2	_	0.4	V _{CCI0} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCI0} + 0.15	-0.24	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCI0} + 0.24	0.25 × V _{CCI0}	0.75 × V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCI0} + 0.15	-0.24	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCI0} + 0.24	0.25 × V _{CCI0}	0.75 × V _{CCIO}	14	-14

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 4 of 4)

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIL
PLD-Transceiver Interface											
Interface speed (F324 and smaller package)	_	25	_	125	25		125	25	_	125	MHz
Interface speed (F484 and larger package)	_	25	_	156.25	25	_	156.25	25	_	156.25	MHz
Digital reset pulse width	_		Minimum is 2 parallel clock cycles								

Notes to Table 1–21:

(1) This specification is valid for transmitter output jitter specification with a maximum total jitter value of 112 ps, typically for 3.125 Gbps SRIO and XAUI protocols.

(2) The minimum reconfig_clk frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter Only** mode. The minimum reconfig_clk frequency is 37.5 MHz if the transceiver channel is configured in **Receiver Only** or **Receiver and Transmitter** mode.

(3) The device cannot tolerate prolonged operation at this absolute maximum.

- (4) The rate matcher supports only up to ±300 parts per million (ppm).
- (5) Supported for the F169 and F324 device packages only.
- (6) Supported for the F484, F672, and F896 device packages only. Pending device characterization.
- (7) To support CDR ppm tolerance greater than ±300 ppm, implement ppm detector in user logic and configure CDR to Manual Lock Mode.
- (8) Asynchronous spread-spectrum clocking is not supported.
- (9) For the EP4CGX30 (F484 package only), EP4CGX50, and EP4CGX75 devices, the CDR ppl tolerance is ±200 ppm.
- (10) Time taken until pll_locked goes high after pll_powerdown deasserts.
- (11) Time that the CDR must be kept in lock-to-reference mode after rx_analogreset deasserts and before rx_locktodata is asserted in manual mode.

(12) Time taken to recover valid data after the rx_locktodata signal is asserted in manual mode (Figure 1-2), or after rx_freqlocked signal goes high in automatic mode (Figure 1-3).

(13) Time taken to recover valid data after the rx_locktodata signal is asserted in manual mode.

- (14) Time taken to recover valid data after the $rx_freqlocked$ signal goes high in automatic mode.
- (15) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.